

L Number	Hits	Search Text	DB	Time stamp
1	3924105	(lamination laminate laminated laminating) wiht (carrier substrate board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 08:37
2	2531487	semiconductor die dice chip ic (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 08:39
3	1291556	antenna meander slot patch meandering meandered	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:55
4	110061	((lamination laminate laminated laminating) wiht (carrier substrate board)) and (semiconductor die dice chip ic (integrated adj circuit)) and (antenna meander slot patch meandering meandered)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 08:41
5	18523	((lamination laminate laminated laminating) wiht (carrier substrate board)) same (semiconductor die dice chip ic (integrated adj circuit)) same (antenna meander slot patch meandering meandered)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 08:42
6	2516	((lamination laminate laminated laminating) wiht (carrier substrate board)) same (semiconductor die dice chip ic (integrated adj circuit)) same (antenna meander slot patch meandering meandered)) same (wire wiring trace)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 08:43
7	665	((lamination laminate laminated laminating) wiht (carrier substrate board)) same (semiconductor die dice chip ic (integrated adj circuit)) same (antenna meander slot patch meandering meandered)) same (wire wiring trace)) same (pad padding bond)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 08:44
8	355	((lamination laminate laminated laminating) wiht (carrier substrate board)) same (semiconductor die dice chip ic (integrated adj circuit)) same (antenna meander slot patch meandering meandered)) same (wire wiring trace)) same (pad padding bond)) and (ball bump bga pbga)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 08:45
9	367953	antenna meander patch meandering meandered	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:55
10	8266	(antenna meander patch meandering meandered) same ((lamination laminate laminated laminating) wiht (carrier substrate board)) same (semiconductor die dice chip ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:02
11	403	((antenna meander patch meandering meandered) same ((lamination laminate laminated laminating) wiht (carrier substrate board)) same (semiconductor die dice chip ic (integrated adj circuit))) and trace and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:03
12	135	((antenna meander patch meandering meandered) same ((lamination laminate laminated laminating) wiht (carrier substrate board)) same (semiconductor die dice chip ic (integrated adj circuit))) and trace and wire) and (bga bump ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:03

13	104	(((antenna meander patch meandering meandered) same ((lamination laminate laminated laminating) wiht (carrier substrate board)) same (semiconductor die dice chip ic (integrated adj circuit))) and trace and wire) and (bga bump ball) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:03
14	74	(((antenna meander patch meandering meandered) same ((lamination laminate laminated laminating) wiht (carrier substrate board)) same (semiconductor die dice chip ic (integrated adj circuit))) and trace and wire) and (bga bump ball) and pad) not (((((lamination laminate laminated laminating) wiht (carrier substrate board)) same (semiconductor die dice chip ic (integrated adj circuit)) same (antenna meander slot patch meandering meandered)) same (wire wiring trace)) same (pad padding bond)) and (ball bump bga pbga))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:03